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United States Design Patent

Wang

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(54) **EARPHONE**

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(52) **U.S. Cl.**
USPC **D14/223**

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381/380–381, 322, 328
CPC H04R 1/10; H04R 25/00; H04R 25/02;
H04R 1/1066; H04R 1/1016; H04R
5/033; H04R 5/0335; H04R 1/1083;
H04R 1/105; H04R 1/1058; H04R 1/1091
See application file for complete search history.

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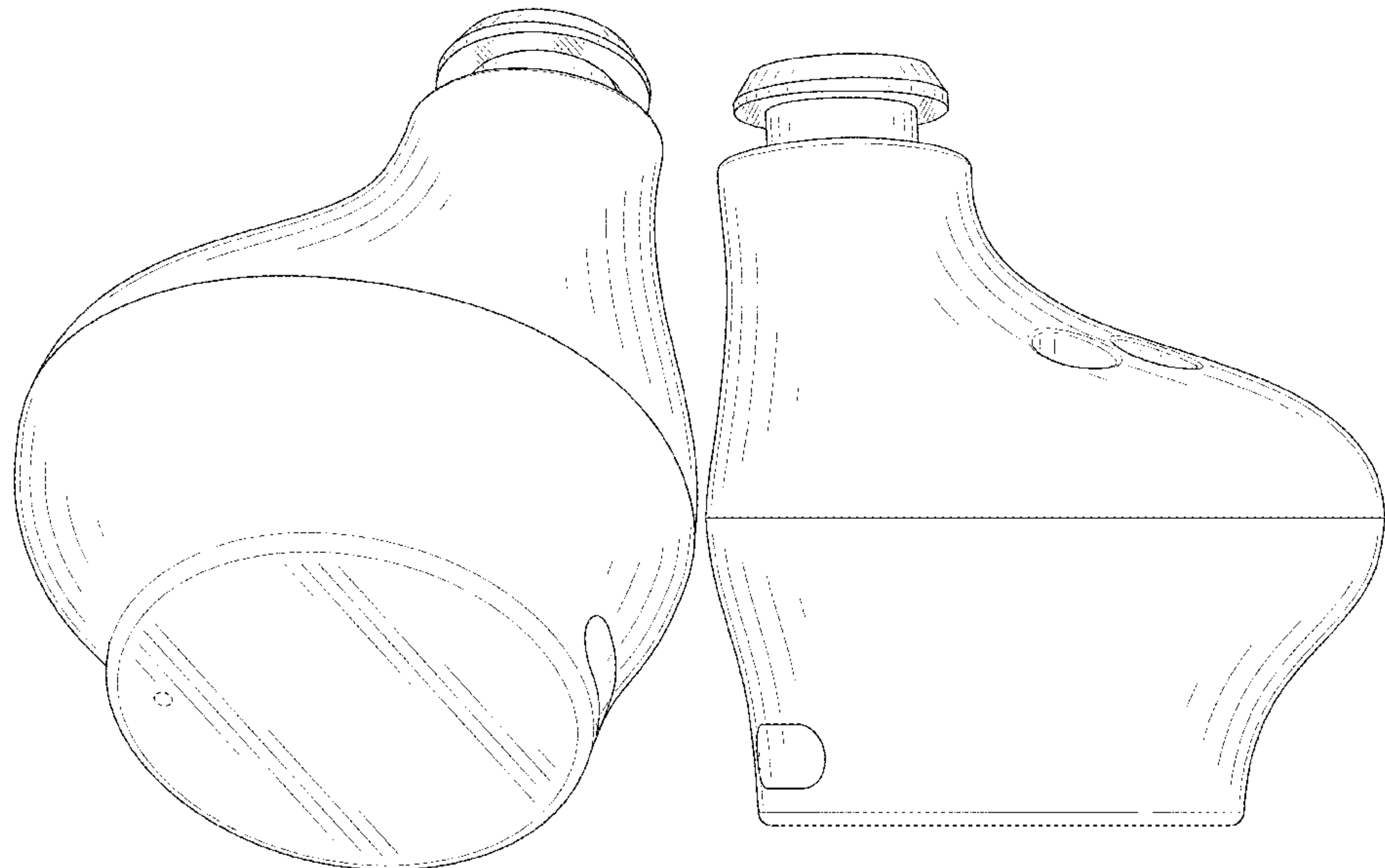
(57) **CLAIM**

The ornamental design for an earphone, as shown and described.

DESCRIPTION

FIG. 1 is a front perspective view of an earphone showing our design.
FIG. 2 is a bottom rear perspective view of the earphone.
FIG. 3 is a front elevation view thereof.
FIG. 4 is a rear elevation view thereof.
FIG. 5 is a left side elevation view thereof.
FIG. 6 is a right side elevation view thereof.
FIG. 7 is a top plan view thereof; and,
FIG. 8 is a bottom plan view thereof.
The broken lines depict portions of the earphone that form no part of the claimed design.

1 Claim, 8 Drawing Sheets



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FIG. 1

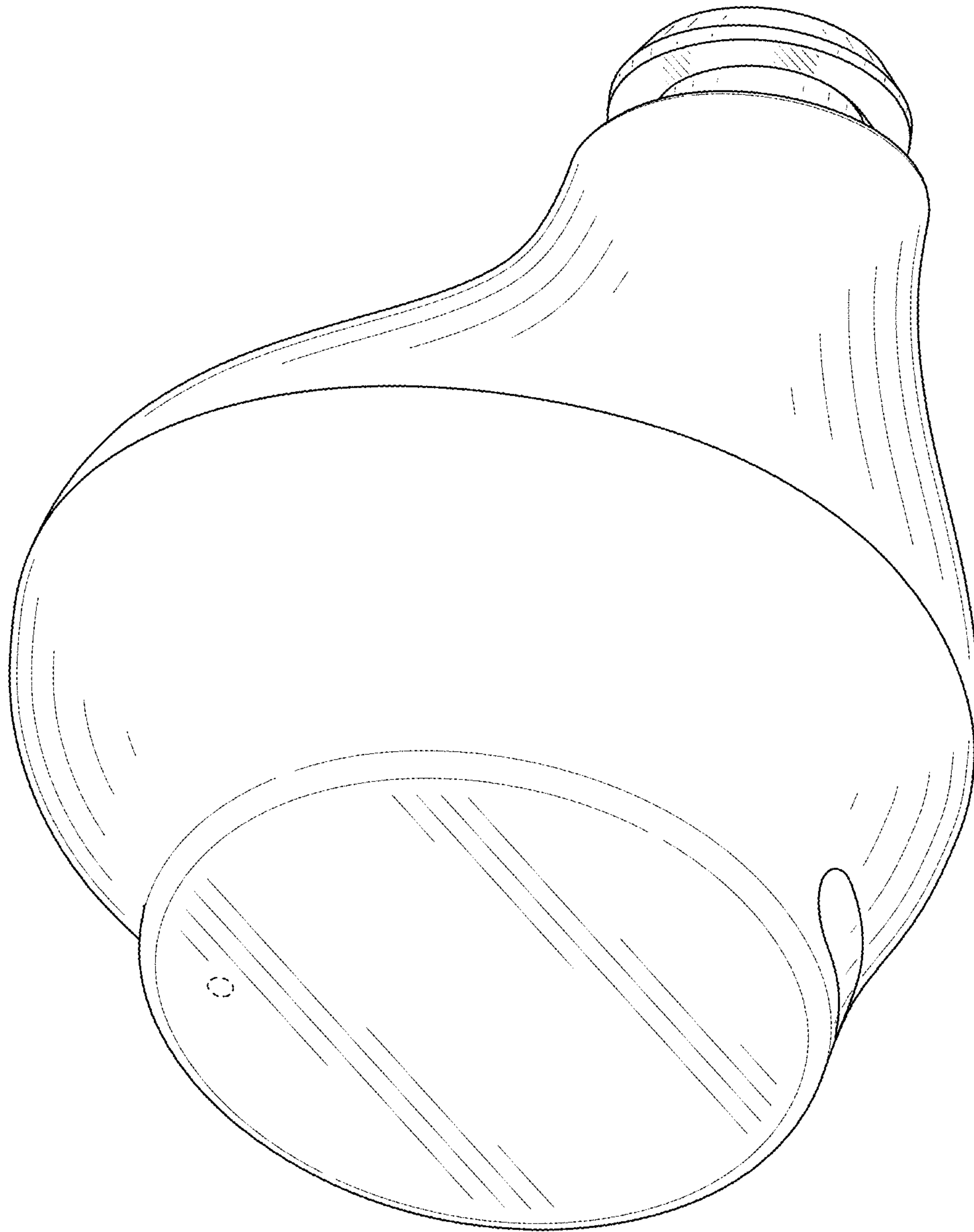


FIG. 2

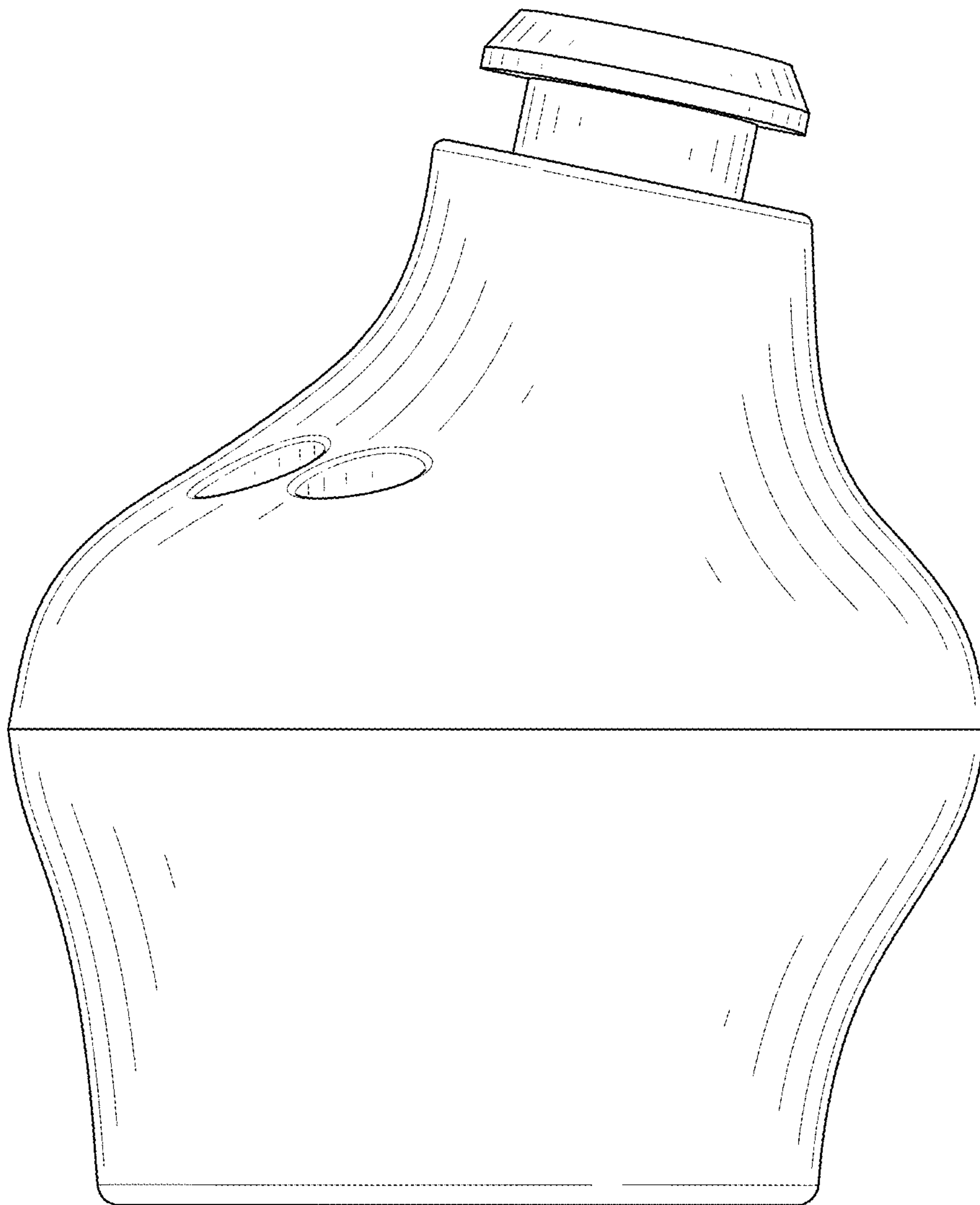


FIG. 3

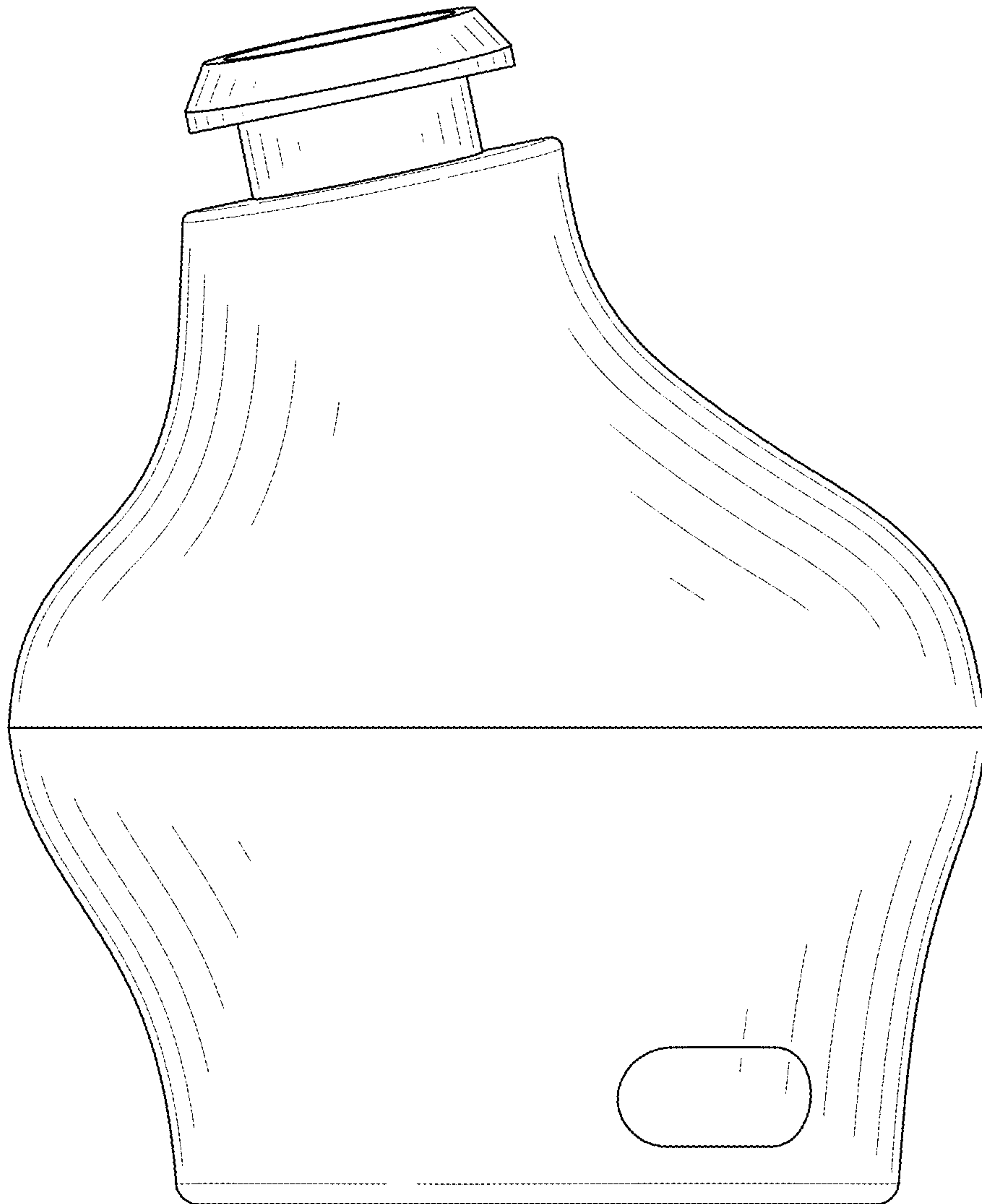


FIG. 4

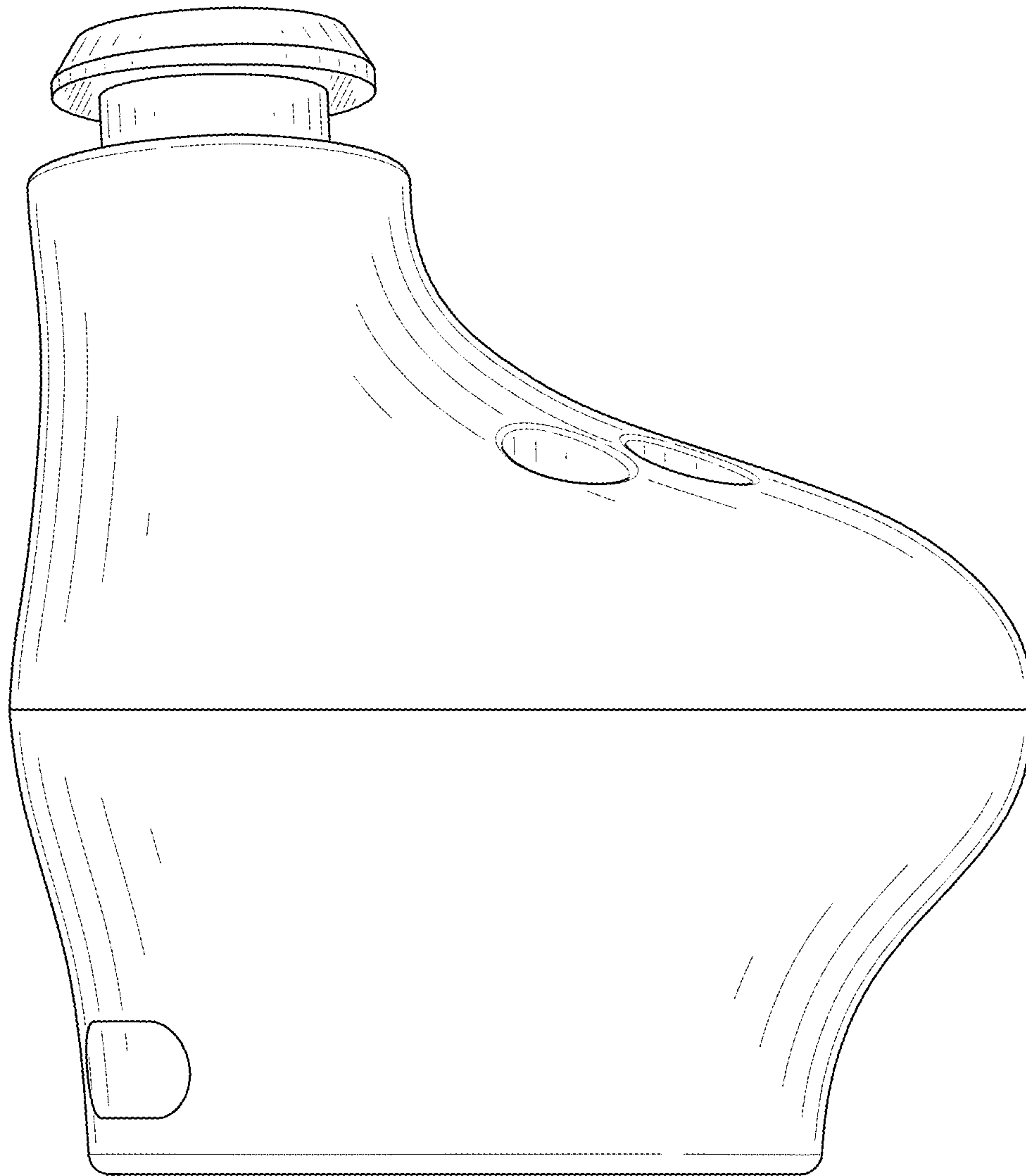


FIG. 5

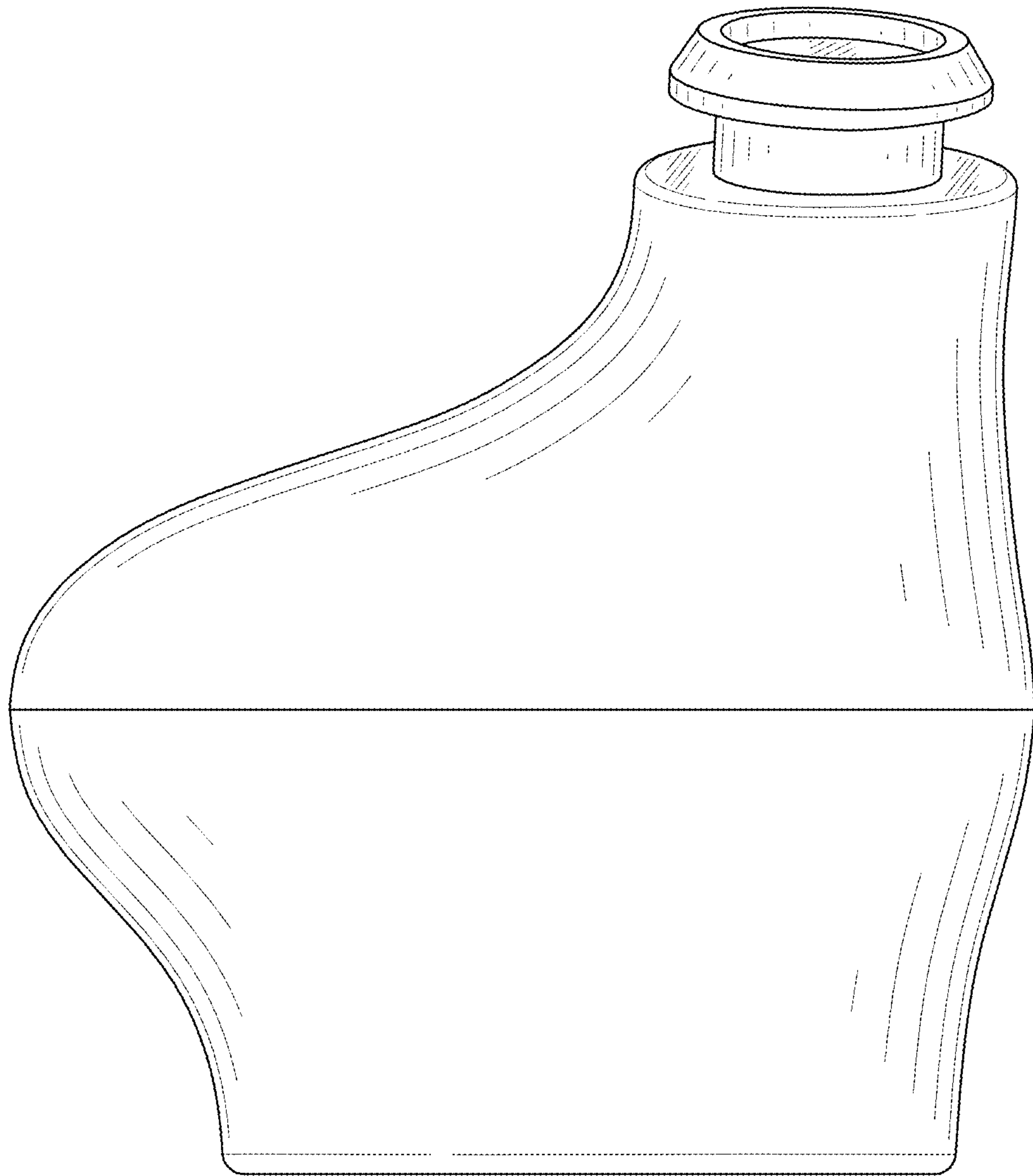


FIG. 6

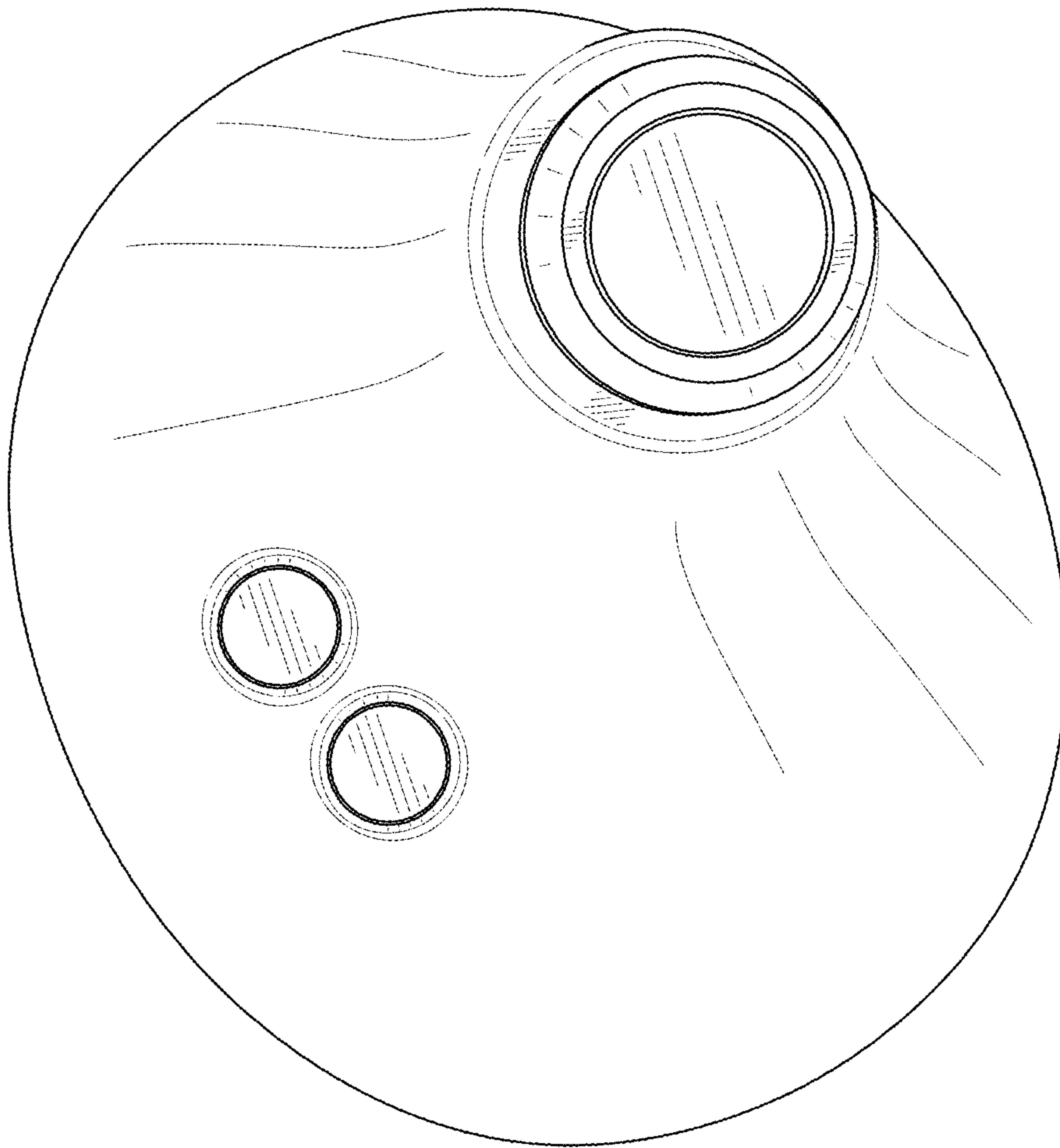


FIG. 7

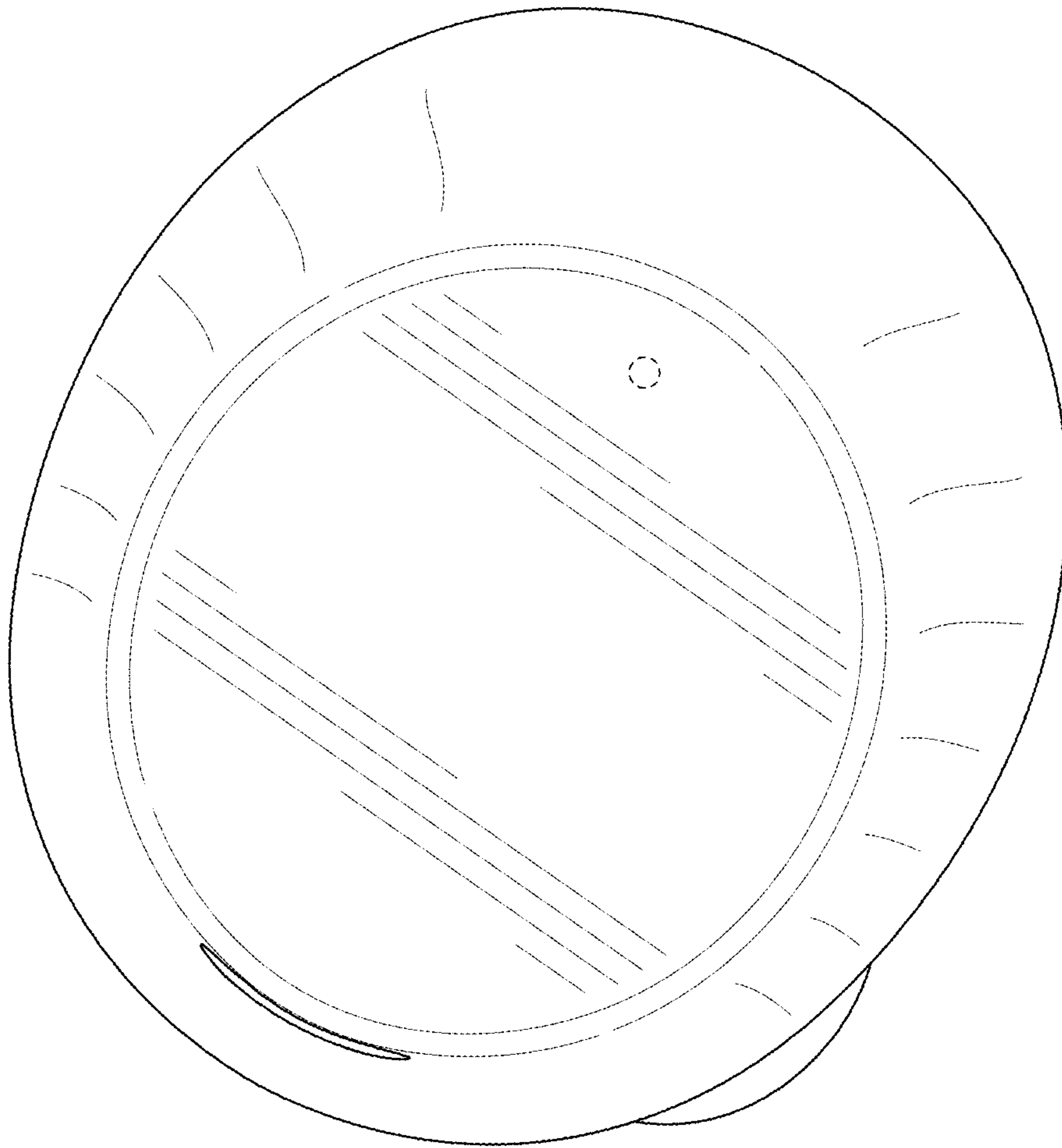


FIG. 8